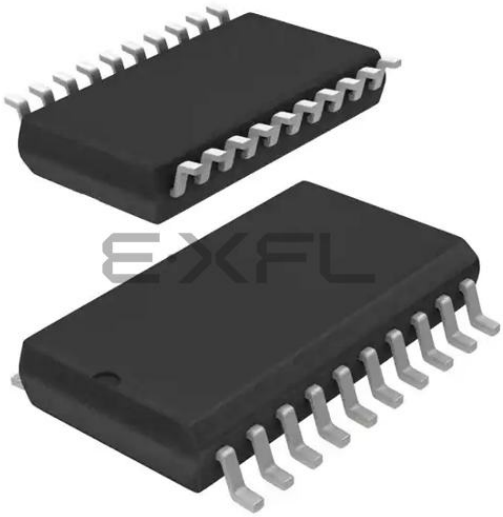


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	F²MC-8FX
Core Size	8-Bit
Speed	16MHz
Connectivity	LINbus, UART/USART
Peripherals	LVD, POR, PWM, WDT
Number of I/O	17
Program Memory Size	20KB (20K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	496 x 8
Voltage - Supply (Vcc/Vdd)	2.4V ~ 5.5V
Data Converters	A/D 6x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SOIC (0.295", 7.50mm Width)
Supplier Device Package	20-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb95f564kpf-g-sne2

2. Packages And Corresponding Products

- MB95560H Series

Part number / Package	MB95F562H	MB95F562K	MB95F563H	MB95F563K	MB95F564H	MB95F564K
WNP032	O	O	O	O	O	O
SOJ020	O	O	O	O	O	O
STG020	O	O	O	O	O	O
STB016	X	X	X	X	X	X
SO016	X	X	X	X	X	X
PDA008	X	X	X	X	X	X
SOD008	X	X	X	X	X	X

- MB95570H Series

Part number / Package	MB95F572H	MB95F572K	MB95F573H	MB95F573K	MB95F574H	MB95F574K
WNP032	X	X	X	X	X	X
SOJ020	X	X	X	X	X	X
STG020	X	X	X	X	X	X
STB016	X	X	X	X	X	X
SO016	X	X	X	X	X	X
PDA008	O	O	O	O	O	O
SOD008	O	O	O	O	O	O

- MB95580H Series

Part number / Package	MB95F582H	MB95F582K	MB95F583H	MB95F583K	MB95F584H	MB95F584K
WNP032	O	O	O	O	O	O
SOJ020	X	X	X	X	X	X
STG020	X	X	X	X	X	X
STB016	O	O	O	O	O	O
SO016	O	O	O	O	O	O
PDA008	X	X	X	X	X	X
SOD008	X	X	X	X	X	X

O: Available
X: Unavailable

5. Pin Functions (MB95560H Series, 32 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	PF1	B	General-purpose I/O port
	X1		Main clock I/O oscillation pin
2	PF0	B	General-purpose I/O port
	X0		Main clock input oscillation pin
3	V_{SS}	—	Power supply pin (GND)
4	PG2	C	General-purpose I/O port
	X1A		Subclock I/O oscillation pin
5	PG1	C	General-purpose I/O port
	X0A		Subclock input oscillation pin
6	V_{CC}	—	Power supply pin
7	C	—	Decoupling capacitor connection pin
8	PF2	A	General-purpose I/O port
	$\overline{RST}$		Reset pin Dedicated reset pin on MB95F562H/F563H/F564H
9	P63	E	General-purpose I/O port High-current pin
	TO11		8/16-bit composite timer ch. 1 output pin
10	P62	E	General-purpose I/O port High-current pin
	TO10		8/16-bit composite timer ch. 1 output pin
11	NC	—	It is an internally connected pin. Always leave it unconnected.
12			
13			
14			
15	P00	D	General-purpose I/O port High-current pin
	AN00		A/D converter analog input pin
16	P64	E	General-purpose I/O port High-current pin
	EC1		8/16-bit composite timer ch. 1 clock input pin
17	P01	D	General-purpose I/O port High-current pin
	AN01		A/D converter analog input pin
18	P02	D	General-purpose I/O port High-current pin
	INT02		External interrupt input pin
	AN02		A/D converter analog input pin
	SCK		LIN-UART clock I/O pin

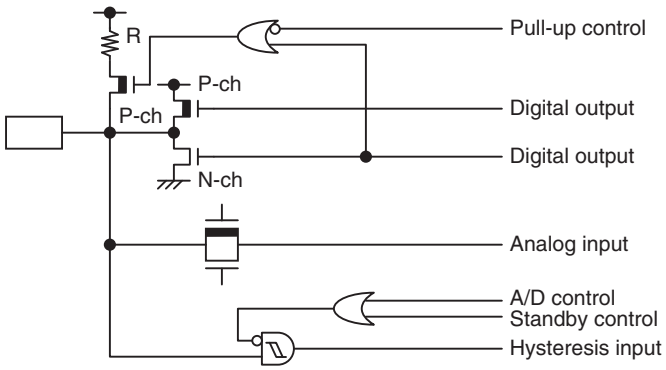
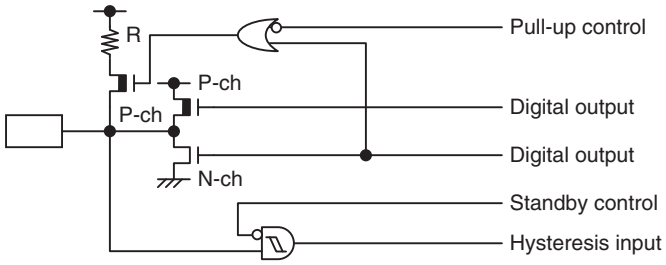
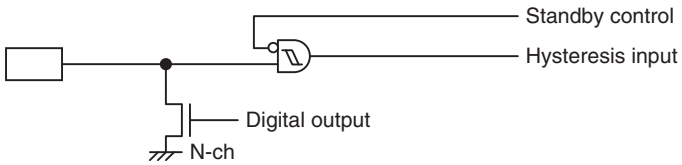
Pin no.	Pin name	I/O circuit type*	Function
16	P04	D	General-purpose I/O port
	INT04		External interrupt input pin
	AN04		A/D converter analog input pin
	SIN		LIN-UART data input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
17	P05	D	General-purpose I/O port High-current pin
	INT05		External interrupt input pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
18	P06	E	General-purpose I/O port High-current pin
	INT06		External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
19	P07	E	General-purpose I/O port High-current pin
	INT07		External interrupt input pin
20	P12	F	General-purpose I/O port
	EC0		8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

*: For the I/O circuit types, see “I/O Circuit Type”.

7. Pin Functions (MB95570H Series, 8 pins)

Pin no.	Pin name	I/O circuit type*	Function
1	V_{SS}	—	Power supply pin (GND)
2	V_{CC}	—	Power supply pin
3	C	—	Decoupling capacitor connection pin
4	PF2	A	General-purpose I/O port
	$\overline{RST}$		Reset pin Dedicated reset pin on MB95F572H/F573H/F574H
5	P04	D	General-purpose I/O port
	INT04		External interrupt input pin
	AN04		A/D converter analog input pin
	EC0		8/16-bit composite timer ch. 0 clock input pin
6	P05	D	General-purpose I/O port High-current pin
	AN05		A/D converter analog input pin
	TO00		8/16-bit composite timer ch. 0 output pin
7	P06	E	General-purpose I/O port High-current pin
	INT06		External interrupt input pin
	TO01		8/16-bit composite timer ch. 0 output pin
8	P12	F	General-purpose I/O port
	EC0		8/16-bit composite timer ch. 0 clock input pin
	DBG		DBG input pin

*: For the I/O circuit types, see “I/O Circuit Type”.

Type	Circuit	Remarks
D		• CMOS output • Hysteresis input • Pull-up control available • Analog input
E		• CMOS output • Hysteresis input • Pull-up control available
F		• N-ch open drain output • Hysteresis input

11. Handling Precautions

Any semiconductor devices have inherently a certain rate of failure. The possibility of failure is greatly affected by the conditions in which they are used (circuit conditions, environmental conditions, etc.). This page describes precautions that must be observed to minimize the chance of failure and to obtain higher reliability from your Cypress semiconductor devices.

11.1 Precautions for Product Design

This section describes precautions when designing electronic equipment using semiconductor devices.

- **Absolute Maximum Ratings**

Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of certain established limits, called absolute maximum ratings. Do not exceed these ratings.

- **Recommended Operating Conditions**

Recommended operating conditions are normal operating ranges for the semiconductor device. All the device's electrical characteristics are warranted when operated within these ranges.

Always use semiconductor devices within the recommended operating conditions. Operation outside these ranges may adversely affect reliability and could result in device failure.

No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their sales representative beforehand.

- **Processing and Protection of Pins**

  These precautions must be followed when handling the pins which connect semiconductor devices to power supply and input/output functions.

  (1) Preventing Over-Voltage and Over-Current Conditions

  Exposure to voltage or current levels in excess of maximum ratings at any pin is likely to cause deterioration within the device, and in extreme cases leads to permanent damage of the device. Try to prevent such overvoltage or over-current conditions at the design stage.

  (2) Protection of Output Pins

  Shorting of output pins to supply pins or other output pins, or connection to large capacitance can cause large current flows. Such conditions if present for extended periods of time can damage the device.

  Therefore, avoid this type of connection.

  (3) Handling of Unused Input Pins

  Unconnected input pins with very high impedance levels can adversely affect stability of operation. Such pins should be connected through an appropriate resistance to a power supply pin or ground pin.

- **Latch-up**

  Semiconductor devices are constructed by the formation of P-type and N-type areas on a substrate. When subjected to abnormally high voltages, internal parasitic PNPN junctions (called thyristor structures) may be formed, causing large current levels in excess of several hundred mA to flow continuously at the power supply pin. This condition is called latch-up.

  CAUTION: The occurrence of latch-up not only causes loss of reliability in the semiconductor device, but can cause injury or damage from high heat, smoke or flame. To prevent this from happening, do the following:

  (1) Be sure that voltages applied to pins do not exceed the absolute maximum ratings. This should include attention to abnormal noise, surge levels, etc.

  (2) Be sure that abnormal current flows do not occur during the power-on sequence.

- **Observance of Safety Regulations and Standards**

  Most countries in the world have established standards and regulations regarding safety, protection from electromagnetic interference, etc. Customers are requested to observe applicable regulations and standards in the design of products.

- **Fail-Safe Design**

  Any semiconductor devices have inherently a certain rate of failure. You must protect against injury, damage or loss from such failures by incorporating safety design measures into your facility and equipment such as redundancy, fire protection, and prevention of over-current levels and other abnormal operating conditions.

- **Precautions Related to Usage of Devices**

  Cypress semiconductor devices are intended for use in standard applications (computers, office automation and other office equipment, industrial, communications, and measurement equipment, personal or household devices, etc.).

  CAUTION: Customers considering the use of our products in special applications where failure or abnormal operation may directly affect human lives or cause physical injury or property damage, or where extremely high levels of reliability are demanded (such as aerospace systems, atomic energy controls, sea floor repeaters, vehicle operating controls, medical devices for life support, etc.) are requested to consult with sales representatives before such use. The company will not be responsible for damages arising from such use without prior approval.

Supply voltage must be stabilized.
A malfunction may occur when power supply voltage fluctuates rapidly even though the fluctuation is within the guaranteed operating range of the V_{CC} power supply voltage.
As a rule of voltage stabilization, suppress voltage fluctuation so that the fluctuation in V_{CC} ripple (p-p value) at the commercial frequency (50 Hz/60 Hz) does not exceed 10% of the standard V_{CC} value, and the transient fluctuation rate does not exceed 0.1 V/ms at a momentary fluctuation such as switching the power supply.

- Notes on using the external clock
  When an external clock is used, oscillation stabilization wait time is required for power-on reset, wake-up from subclock mode or stop mode.

13. Pin Connection

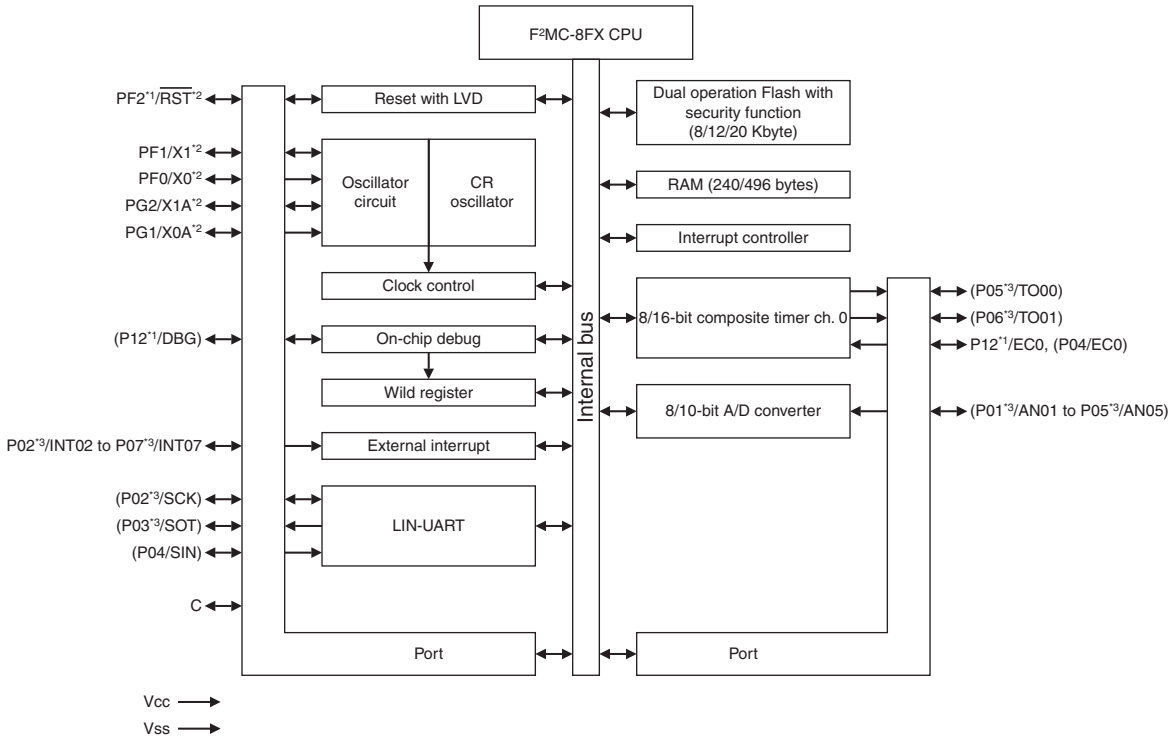
- Treatment of unused pins
  If an unused input pin is left unconnected, a component may be permanently damaged due to malfunctions or latch-ups. Always pull up or pull down an unused input pin through a resistor of at least 2 kΩ. Set an unused input/output pin to the output state and leave it unconnected, or set it to the input state and treat it the same as an unused input pin. If there is an unused output pin, leave it unconnected.

- Power supply pins
  To reduce unnecessary electro-magnetic emission, prevent malfunctions of strobe signals due to an increase in the ground level, and conform to the total output current standard, always connect the V_{CC} pin and the V_{SS} pin to the power supply and ground outside the device. In addition, connect the current supply source to the V_{CC} pin and the V_{SS} pin with low impedance.
  It is also advisable to connect a ceramic capacitor of approximately 0.1 µF as a decoupling capacitor between the V_{CC} pin and the V_{SS} pin at a location close to this device.

- DBG pin
  Connect the DBG pin to an external pull-up resistor of 2 kΩ or above.
  After power-on, ensure that the DBG pin does not stay at “L” level until the reset output is released.
  The DBG pin becomes a communication pin in debug mode. Since the actual pull-up resistance depends on the tool used and the interconnection length, refer to the tool document when selecting a pull-up resistor.

- $\overline{\text{RST}}$ pin
  Connect the $\overline{\text{RST}}$ pin to an external pull-up resistor of 2 kΩ or above.
  To prevent the device from unintentionally entering the reset mode due to noise, minimize the interconnection length between a pull-up resistor and the $\overline{\text{RST}}$ pin and that between a pull-up resistor and the V_{CC} pin when designing the layout of the printed circuit board.
  The PF2/$\overline{\text{RST}}$ pin functions as the reset input/output pin after power-on. In addition, the reset output of the PF2/$\overline{\text{RST}}$ pin can be enabled by the RSTOE bit in the SYSC register, and the reset input function and the general purpose I/O function can be selected by the RSTEN bit in the SYSC register.
- C pin
  Use a ceramic capacitor or a capacitor with equivalent frequency characteristics. The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_S. For the connection to a decoupling capacitor C_S, see the diagram below. To prevent the device from unintentionally entering a mode to which the device is not set to transit due to noise, minimize the distance between the C pin and C_S and the distance between C_S and the V_{SS} pin when designing the layout of a printed circuit board.

16. Block Diagram (MB95580H Series)



*1: PF2 and P12 are N-ch open drain pins.

*2: Software option

*3: P01 to P03 and P05 to P07 are high-current pins.

Note: Pins in parentheses indicate that functions of those pins are shared among different resources.

Address	Register abbreviation	Register name	R/W	Initial value
0F83H	WRARH1	Wild register address setting register (upper) ch. 1	R/W	00000000B
0F84H	WRARL1	Wild register address setting register (lower) ch. 1	R/W	00000000B
0F85H	WRDR1	Wild register data setting register ch. 1	R/W	00000000B
0F86H	WRARH2	Wild register address setting register (upper) ch. 2	R/W	00000000B
0F87H	WRARL2	Wild register address setting register (lower) ch. 2	R/W	00000000B
0F88H	WRDR2	Wild register data setting register ch. 2	R/W	00000000B
0F89H to 0F91H	—	(Disabled)	—	—
0F92H	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	00000000B
0F93H	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	00000000B
0F94H	T01DR	8/16-bit composite timer 01 data register	R/W	00000000B
0F95H	T00DR	8/16-bit composite timer 00 data register	R/W	00000000B
0F96H	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	00000000B
0F97H	T11CR0	8/16-bit composite timer 11 status control register 0	R/W	00000000B
0F98H	T10CR0	8/16-bit composite timer 10 status control register 0	R/W	00000000B
0F99H	T11DR	8/16-bit composite timer 11 data register	R/W	00000000B
0F9AH	T10DR	8/16-bit composite timer 10 data register	R/W	00000000B
0F9BH	TMCR1	8/16-bit composite timer 10/11 timer mode control register	R/W	00000000B
0F9CH to 0FBBH	—	(Disabled)	—	—
0FBCH	BGR1	LIN-UART baud rate generator register 1	R/W	00000000B
0FBDH	BGR0	LIN-UART baud rate generator register 0	R/W	00000000B
0FBEH to 0FC2H	—	(Disabled)	—	—
0FC3H	AIDRL	A/D input disable register (lower)	R/W	00000000B
0FC4H to 0FE3H	—	(Disabled)	—	—
0FE4H	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXXB
0FE5H	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXXB
0FE6H	—	(Disabled)	—	—
0FE7H	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXXB
0FE8H	SYSC	System configuration register	R/W	11000011B
0FE9H	CMCR	Clock monitoring control register	R/W	00000000B
0FEAH	CMDR	Clock monitoring data register	R	00000000B

Address	Register abbreviation	Register name	R/W	Initial value
0FEB$_H$	WDTH	Watchdog timer selection ID register (upper)	R	XXXXXXXX$_B$
0FEC$_H$	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXX$_B$
0FED$_H$ to 0FFF$_H$	—	(Disabled)	—	—

• R/W access symbols
  R/W : Readable / Writable
  R : Read only

• Initial value symbols
  0 : The initial value of this bit is “0”.
  1 : The initial value of this bit is “1”.
  X : The initial value of this bit is undefined.

Note: Do not write to an address that is “(Disabled)”. If a “(Disabled)” address is read, an indeterminate value is returned.

Address	Register abbreviation	Register name	R/W	Initial value
006C$_H$	ADC1	8/10-bit A/D converter control register 1	R/W	00000000$_B$
006D$_H$	ADC2	8/10-bit A/D converter control register 2	R/W	00000000$_B$
006E$_H$	ADDH	8/10-bit A/D converter data register (upper)	R/W	00000000$_B$
006F$_H$	ADDL	8/10-bit A/D converter data register (lower)	R/W	00000000$_B$
0070$_H$	—	(Disabled)	—	—
0071$_H$	FSR2	Flash memory status register 2	R/W	00000000$_B$
0072$_H$	FSR	Flash memory status register	R/W	000X0000$_B$
0073$_H$	SWRE0	Flash memory sector write control register 0	R/W	00000000$_B$
0074$_H$	FSR3	Flash memory status register 3	R	000XXXXX$_B$
0075$_H$	FSR4	Flash memory status register 4	R/W	00000000$_B$
0076$_H$	WREN	Wild register address compare enable register	R/W	00000000$_B$
0077$_H$	WROR	Wild register data test setting register	R/W	00000000$_B$
0078$_H$	—	Mirror of register bank pointer (RP) and direct bank pointer (DP)	—	—
0079$_H$	ILR0	Interrupt level setting register 0	R/W	11111111$_B$
007A$_H$	ILR1	Interrupt level setting register 1	R/W	11111111$_B$
007B$_H$, 007C$_H$	—	(Disabled)	—	—
007D$_H$	ILR4	Interrupt level setting register 4	R/W	11111111$_B$
007E$_H$	ILR5	Interrupt level setting register 5	R/W	11111111$_B$
007F$_H$	—	(Disabled)	—	—
0F80$_H$	WRARH0	Wild register address setting register (upper) ch. 0	R/W	00000000$_B$
0F81$_H$	WRARL0	Wild register address setting register (lower) ch. 0	R/W	00000000$_B$
0F82$_H$	WRDR0	Wild register data setting register ch. 0	R/W	00000000$_B$
0F83$_H$	WRARH1	Wild register address setting register (upper) ch. 1	R/W	00000000$_B$
0F84$_H$	WRARL1	Wild register address setting register (lower) ch. 1	R/W	00000000$_B$
0F85$_H$	WRDR1	Wild register data setting register ch. 1	R/W	00000000$_B$
0F86$_H$	WRARH2	Wild register address setting register (upper) ch. 2	R/W	00000000$_B$
0F87$_H$	WRARL2	Wild register address setting register (lower) ch. 2	R/W	00000000$_B$
0F88$_H$	WRDR2	Wild register data setting register ch. 2	R/W	00000000$_B$
0F89$_H$ to 0F91$_H$	—	(Disabled)	—	—
0F92$_H$	T01CR0	8/16-bit composite timer 01 status control register 0	R/W	00000000$_B$
0F93$_H$	T00CR0	8/16-bit composite timer 00 status control register 0	R/W	00000000$_B$
0F94$_H$	T01DR	8/16-bit composite timer 01 data register	R/W	00000000$_B$
0F95$_H$	T00DR	8/16-bit composite timer 00 data register	R/W	00000000$_B$
0F96$_H$	TMCR0	8/16-bit composite timer 00/01 timer mode control register	R/W	00000000$_B$
0F97$_H$ to 0FC2$_H$	—	(Disabled)	—	—

Address	Register abbreviation	Register name	R/W	Initial value
0FC3H	AIDRL	A/D input disable register (lower)	R/W	00000000B
0FC4H to 0FE3H	—	(Disabled)	—	—
0FE4H	CRTH	Main CR clock trimming register (upper)	R/W	000XXXXXB
0FE5H	CRTL	Main CR clock trimming register (lower)	R/W	000XXXXXB
0FE6H	—	(Disabled)	—	—
0FE7H	CRTDA	Main CR clock temperature dependent adjustment register	R/W	000XXXXXB
0FE8H	SYSC	System configuration register	R/W	11000011B
0FE9H	CMCR	Clock monitoring control register	R/W	00000000B
0FEAH	CMDR	Clock monitoring data register	R	00000000B
0FEBH	WDTH	Watchdog timer selection ID register (upper)	R	XXXXXXXXB
0FECH	WDTL	Watchdog timer selection ID register (lower)	R	XXXXXXXXB
0FEDH to 0FFFH	—	(Disabled)	—	—

• R/W access symbols
  R/W : Readable / Writable
  R : Read only

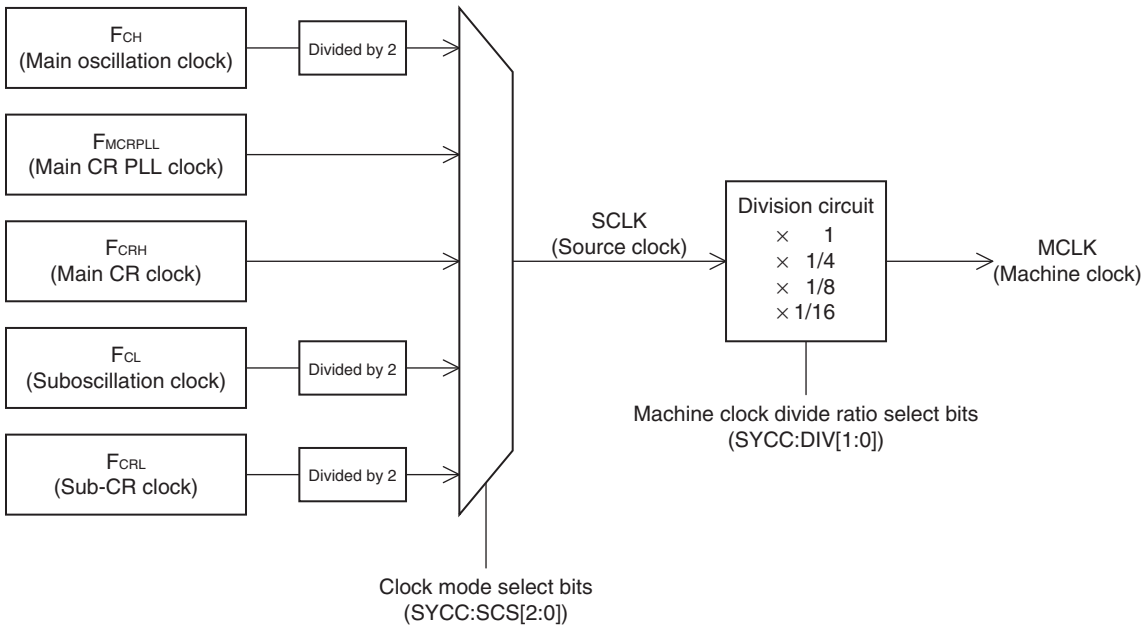
• Initial value symbols
  0 : The initial value of this bit is “0”.
  1 : The initial value of this bit is “1”.
  X : The initial value of this bit is undefined.

Note: Do not write to an address that is “(Disabled)”. If a “(Disabled)” address is read, an indeterminate value is returned.

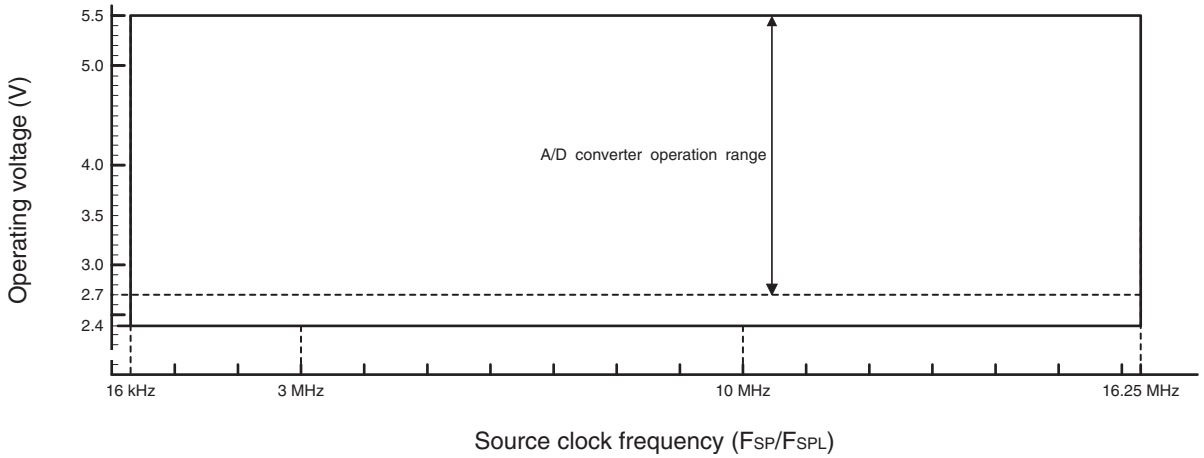
23. Interrupt Source Table (MB95580H Series)

Interrupt source	Interrupt request number	Vector table address		Bit name of interrupt level setting register	Priority order of interrupt sources of the same level (occurring simultaneously)
		Upper	Lower		
External interrupt ch. 4	IRQ00	FFFA$_H$	FFFB$_H$	L00 [1:0]	High
External interrupt ch. 5	IRQ01	FFF8$_H$	FFF9$_H$	L01 [1:0]	
External interrupt ch. 2	IRQ02	FFF6$_H$	FFF7$_H$	L02 [1:0]	
External interrupt ch. 6					
External interrupt ch. 3	IRQ03	FFF4$_H$	FFF5$_H$	L03 [1:0]	
External interrupt ch. 7					
—	IRQ04	FFF2$_H$	FFF3$_H$	L04 [1:0]	
8/16-bit composite timer ch. 0 (lower)	IRQ05	FFF0$_H$	FFF1$_H$	L05 [1:0]	
8/16-bit composite timer ch. 0 (upper)	IRQ06	FFEE$_H$	FFEF$_H$	L06 [1:0]	
LIN-UART (reception)	IRQ07	FFEC$_H$	FFED$_H$	L07 [1:0]	
LIN-UART (transmission)	IRQ08	FFEA$_H$	FFEB$_H$	L08 [1:0]	
—	IRQ09	FFE8$_H$	FFE9$_H$	L09 [1:0]	
—	IRQ10	FFE6$_H$	FFE7$_H$	L10 [1:0]	
—	IRQ11	FFE4$_H$	FFE5$_H$	L11 [1:0]	
—	IRQ12	FFE2$_H$	FFE3$_H$	L12 [1:0]	
—	IRQ13	FFE0$_H$	FFE1$_H$	L13 [1:0]	
—	IRQ14	FFDE$_H$	FFDF$_H$	L14 [1:0]	
—	IRQ15	FFDC$_H$	FFDD$_H$	L15 [1:0]	
—	IRQ16	FFDA$_H$	FFDB$_H$	L16 [1:0]	
—	IRQ17	FFD8$_H$	FFD9$_H$	L17 [1:0]	
8/10-bit A/D converter	IRQ18	FFD6$_H$	FFD7$_H$	L18 [1:0]	
Time-base timer	IRQ19	FFD4$_H$	FFD5$_H$	L19 [1:0]	
Watch prescaler	IRQ20	FFD2$_H$	FFD3$_H$	L20 [1:0]	
—	IRQ21	FFD0$_H$	FFD1$_H$	L21 [1:0]	
—	IRQ22	FFCE$_H$	FFCF$_H$	L22 [1:0]	
Flash memory	IRQ23	FFCC$_H$	FFCD$_H$	L23 [1:0]	Low

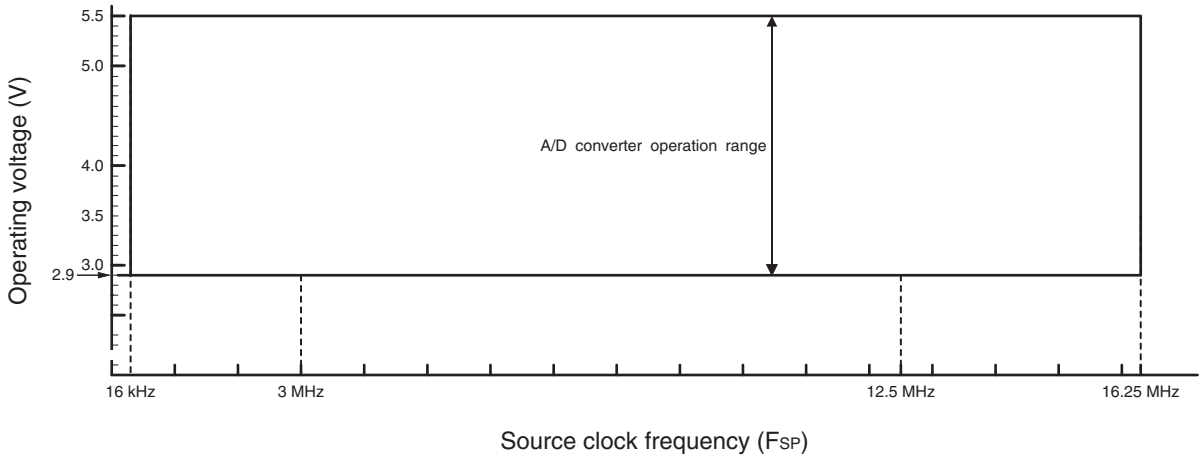
- Schematic diagram of the clock generation block



- Operating voltage - Operating frequency (T_A = –40°C to +85°C)
  Without the on-chip debug function



- Operating voltage - Operating frequency (T_A = –40 °C to +85 °C)
  With the on-chip debug function



24.5 A/D Converter

24.5.1 A/D Converter Electrical Characteristics

(V_{CC} = 2.7 V to 5.5 V, V_{SS} = 0.0 V, T_A = –40 °C to +85 °C)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Resolution	—	—	—	10	bit	
Total error		–3	—	+3	LSB	
Linearity error		–2.5	—	+2.5	LSB	
Differential linearity error		–1.9	—	+1.9	LSB	
Zero transition voltage	V_{0T}	V_{SS} – 1.5 LSB	V_{SS} + 0.5 LSB	V_{SS} + 2.5 LSB	V	
Full-scale transition voltage	V_{FST}	V_{CC} – 4.5 LSB	V_{CC} – 2 LSB	V_{CC} + 0.5 LSB	V	
Compare time	—	1	—	10	µs	4.5 V ≤ V_{CC} ≤ 5.5 V
		3	—	10	µs	2.7 V ≤ V_{CC} < 4.5 V
Sampling time	—	0.6	—	∞	µs	2.7 V ≤ V_{CC} ≤ 5.5 V, with external impedance < 3.3 kΩ
Analog input current	I_{AIN}	–0.3	—	+0.3	µA	
Analog input voltage	V_{AIN}	V_{SS}	—	V_{CC}	V	

24.6 Flash Memory Program/Erase Characteristics

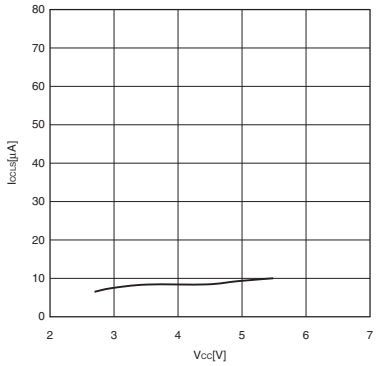
Parameter	Value			Unit	Remarks
	Min	Typ	Max		
Sector erase time (2 Kbyte sector)	—	0.3*1	1.6*2	s	The time of writing 00_H prior to erasure is excluded.
Sector erase time (16 Kbyte sector)	—	0.6*1	3.1*2	s	The time of writing 00_H prior to erasure is excluded.
Byte writing time	—	17	272	µs	System-level overhead is excluded.
Program/erase cycle	100000	—	—	cycle	
Power supply voltage at program/erase	2.4	—	5.5	V	
Flash memory data retention time	5*3	—	—	year	Average T_A = +85 °C

*1: V_{CC} = 5.5 V, T_A = +25 °C, 0 cycle

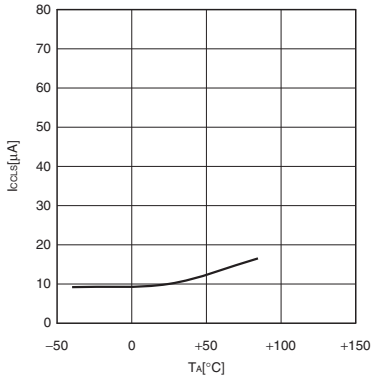
*2: V_{CC} = 2.4 V, T_A = +85 °C, 100000 cycles

*3: This value was converted from the result of a technology reliability assessment. (The value was converted from the result of a high temperature accelerated test using the Arrhenius equation with an average temperature of +85 °C).

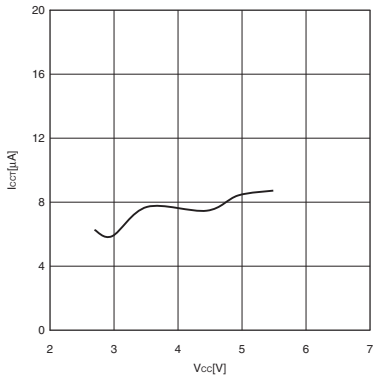
I_{CCLS} – V_{CC}
T_A = +25 °C, F_{MPL} = 16 kHz (divided by 2)
Subsleep mode with the external clock operating



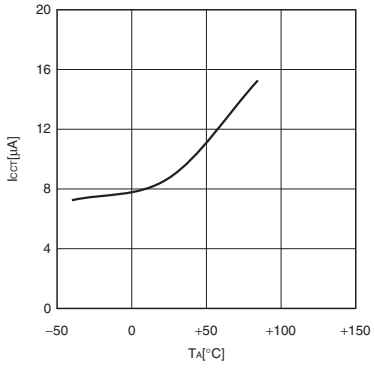
I_{CCLS} – T_A
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Subsleep mode with the external clock operating



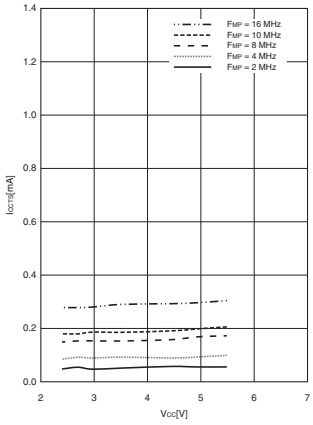
I_{CCT} – V_{CC}
T_A = +25 °C, F_{MPL} = 16 kHz (divided by 2)
Watch mode with the external clock operating



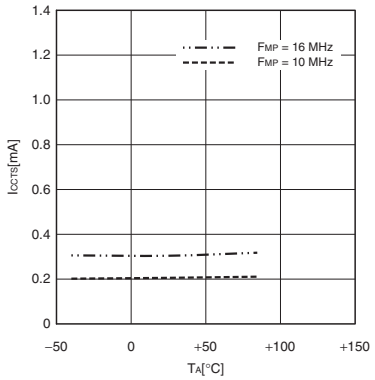
I_{CCT} – T_A
V_{CC} = 5.5 V, F_{MPL} = 16 kHz (divided by 2)
Watch mode with the external clock operating



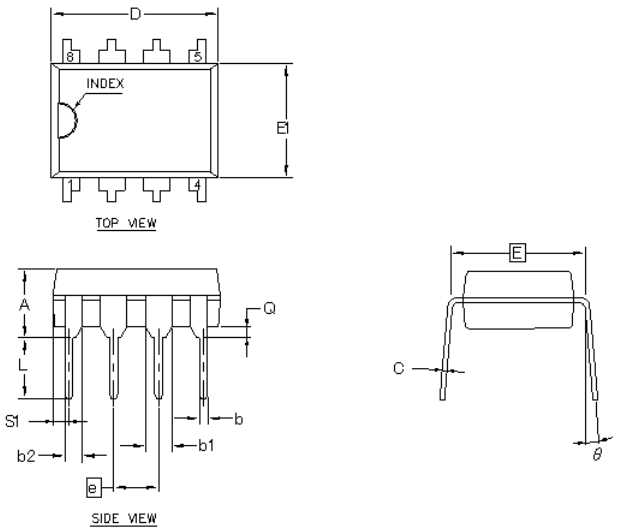
I_{CCTS} – V_{CC}
T_A = +25 °C, F_{MP} = 2, 4, 8, 10, 16 MHz (divided by 2)
Time-base timer mode with the external clock operating



I_{CCTS} – T_A
V_{CC} = 5.5 V, F_{MP} = 10, 16 MHz (divided by 2)
Time-base timer mode with the external clock operating



Package Type	Package Code
DIP 8	PDA008



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	——	——	4.36
L	3.00	——	——
D	9.10	9.40	9.80
E	7.62 TYP		
E1	6.10	6.35	6.60
θ	——	——	15°
c	0.20	0.25	0.30
b	0.38	0.46	0.54
b1	——	1.52	1.82
b2	——	0.99	1.29
e	2.54 TYP		
S1	0.59	0.89	1.24
Q	0.50	——	——

NOTES
1. ALL DIMENSIONS ARE IN MILLIMETER.
2. JEDEC SPECIFICATION NO. REF : N/A

PACKAGE OUTLINE, 8 LEAD PDIP
9.40X6.35X3.86 MM PDA008 REV**

002-16909 **

Page	Section	Details
48	2. Recommended Operating Conditions	Revised note *2. The value is 2.88 V when the low-voltage detection reset is used. → The minimum power supply voltage becomes 2.18 V when a product with the low-voltage detection reset is used.
		Corrected the following statement in note *3. The decoupling capacitor for the V_{CC} pin must have a capacitance larger than C_S. → The decoupling capacitor for the V_{CC} pin must have a capacitance equal to or larger than the capacitance of C_S.
		Revised the remark in "• DBG/$\overline{\text{RST}}$/C pins connection diagram".
49	3. DC Characteristics	Revised the remark of the parameter "Input leak current (Hi-Z output leak current)". When pull-up resistance is disabled → When the internal pull-up resistor is disabled
		Renamed the parameter "Pull-up resistance" to "Internal pull-up resistor".
		Revised the remark of the parameter "Internal pull-up resistor". When pull-up resistance is enabled → When the internal pull-up resistor is enabled
53	4. AC Characteristics (1) Clock Timing	Corrected the pin names of the parameter "Input clock rising time and falling time". X0 → X0, X0A X0, X1 → X0, X1, X0A, X1A